

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>In Sang Yoon</td><td>12/20/2007</td></tr><tr><td>JoHyun Bae</td><td>12/20/2007</td></tr><tr><td>HanGil Shin</td><td>12/20/2007</td></tr></tbody></table>		Name	Execution Date	In Sang Yoon	12/20/2007	JoHyun Bae	12/20/2007	HanGil Shin	12/20/2007
Name	Execution Date								
In Sang Yoon	12/20/2007								
JoHyun Bae	12/20/2007								
HanGil Shin	12/20/2007								
RECEIVING PARTY DATA									
Name:	STATS ChipPAC Ltd.								
Street Address:	5 Yishun Street 23								
City:	Singapore								
State/Country:	SINGAPORE								
Postal Code:	768442								
PROPERTY NUMBERS Total: 1									
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>11965641</td></tr></tbody></table>		Property Type	Number	Application Number:	11965641				
Property Type	Number								
Application Number:	11965641								
CORRESPONDENCE DATA									
Fax Number: (408)738-0881 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>									
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Correspondent Name: LAW OFFICES OF MIKIO ISHIMARU									
Address Line 1: 333 W. EL CAMINO REAL									
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ATTORNEY DOCKET NUMBER:	27-459								
NAME OF SUBMITTER:	Mikio Ishimaru								
Total Attachments: 2 source=27-459_ASSIGNMENT#page1.tif									

CH \$40.00 11965641

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PATENT
REEL: 020295 FRAME: 0735

ASSIGNMENT

WHEREAS, the undersigned (hereinafter termed Assignor(s)) has/have invented certain new and useful improvements in

MOUNTABLE INTEGRATED CIRCUIT PACKAGE SYSTEM WITH STACKING INTERPOSER

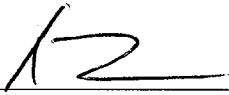
for which a United States patent application has been executed on or before the date of this assignment;

WHEREAS, STATS ChipPAC Ltd., a Corporation of the Republic of Singapore, having a place of business at 5 Yishun Street 23, Singapore 768442 (hereinafter termed Assignee), is desirous of acquiring the entire right, title and interest in and to said application and said invention and improvements thereon, and in and to Letters Patents thereon when granted in the United States and foreign countries;

NOW, THEREFORE, for good and valuable consideration received by said Assignor(s) from said Assignee, the receipt of which is hereby acknowledged by said Assignor(s):

1. Said Assignor(s) does hereby sell, assign, transfer and convey unto said Assignee, the entire right, title and interest in and to said application and said invention and in and to any and all improvements on said invention and in and to any and all improvements on said invention heretofore or hereafter made or acquired by said Assignor(s); and in and to any and all Letters Patent on said invention and/or said improvements that may be granted in the United States or any foreign country, including each and every Letters Patent granted on any application which is a division, continuation, substitution, renewal, or continuation-in-part of any said application, and in and to each and every reissue or extension of said Letters Patent.
2. Said Assignor(s) hereby covenants and agrees to cooperate with said Assignee where said Assignee may enjoy to the fullest extent the right, title and interest herein conveyed. Such cooperation shall include (a) prompt execution of all papers (prepared at the expense of Assignee) which are deemed necessary or desirable by Assignee to perfect in it the right, title and interest herein conveyed, (b) prompt execution of all petitions, oaths, specifications or other papers (prepared at the expense of Assignee) which are deemed necessary or desirable by assignee for prosecuting said application, for filing and prosecuting divisional, continuation, substitution, renewal, continuation-in-part, or additional applications in the United States and/or foreign countries covering said invention and/or said improvements, for filing and prosecuting applications for reissuance of letters patent included herein, or for interference proceedings involving said invention and/or said improvements and (c) prompt assistance and cooperation in the prosecution of interference proceedings involving said invention and/or said improvements and in the adjudication of said Letters Patent, particularly by the disclosure of facts and the production of evidence relating to said invention and/or said improvements, provided the expenses which may be incurred by said Assignor(s) in lending such assistance and cooperation shall be paid by the Assignee.
3. The terms, covenants and conditions of this assignment shall inure to the benefit of said Assignee, its successors, assigns and/or other legal representatives and shall be binding upon said Assignor(s), his/her heirs, legal representatives and assigns.
4. Said Assignor(s) hereby warrants and represents that he/she has not entered into any assignment, contract or understanding in conflict herewith.

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.



In Sang Yoon

Dec. 20. 2007

Date



Witness Signature



Witness Signature

Yang Deok Kyung

Print Witness Name

Park Hyung Sang

Print Witness Name

Dec. 20. 2007

Date

Dec. 20. 2007

Date

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.



JoHyun Bae

Dec. 20. 2007

Date



Witness Signature



Witness Signature

Yang Deok Kyung

Print Witness Name

Park Hyung Sang

Print Witness Name

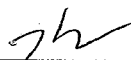
Dec. 20. 2007

Date

Dec. 20. 2007

Date

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.



HanGil Shin

Dec. 20. 2007

Date



Witness Signature



Witness Signature

Yang Deok Kyung

Print Witness Name

Park Hyung Sang

Print Witness Name

Dec. 20. 2007

Date

Dec. 20. 2007

Date